

APPLICATIONS

- ✓ Cellular Phones
- ✓ MCM Boards
- ✓ Wireless Communication Circuits
- ✓ IR LEDs
- ✓ SMART & PCMCIA Cards

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns

FEATURES

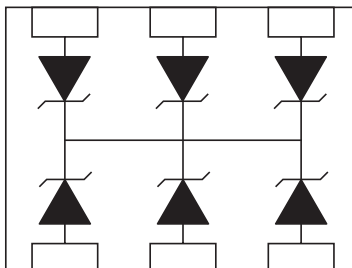
- ✓ ESD Protection > 25 kilovolts
- ✓ Available in Multiple Voltage Types Ranging From 3.3V to 36V
- ✓ 250 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- ✓ Bidirectional Configuration & Monolithic Structure
- ✓ Protects 3 to 5 Lines
- ✓ RoHS in Lead-Free Versions

MECHANICAL CHARACTERISTICS

- ✓ Standard EIA Chip Size: 0406
- ✓ Weight 0.73 milligrams (Approximate)
- ✓ Available in Tin-Lead or Lead-Free Plating
- ✓ Solder Reflow Temperature:
 - Tin-Lead - Sn/Pb, 85/15: 240-245°C
 - Lead-Free - Sn/Ag/Cu, 96/3.5/0.5: 260-270°C
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Plastic & Paper Tape and Reel Per EIA Standard 481
- ✓ Device Marking On Reel
- ✓ Top Contacts: Solder Bump 0.004" in Height (Nominal)



PIN CONFIGURATION

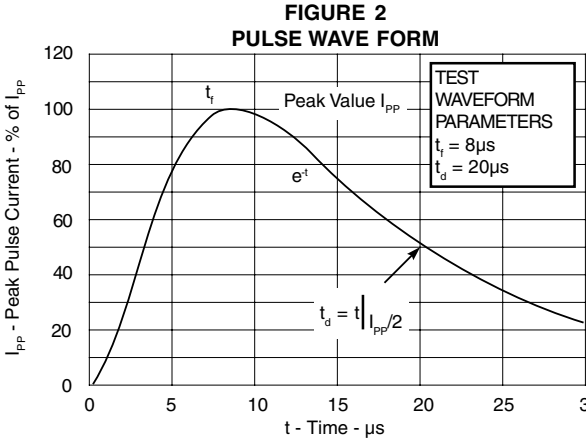
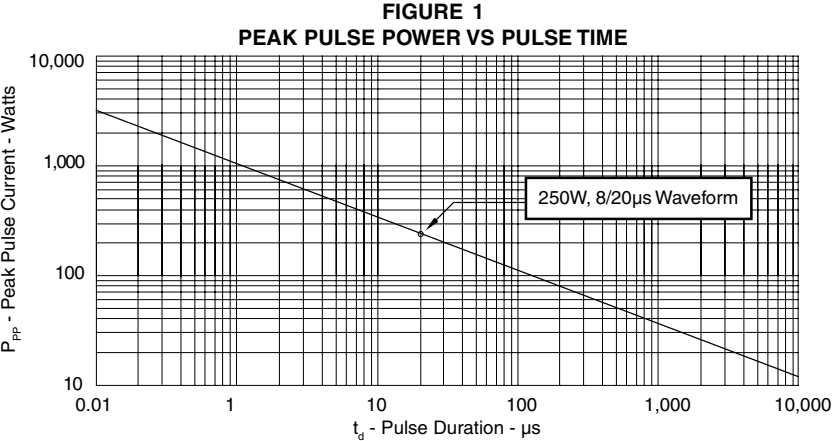


DEVICE CHARACTERISTICS

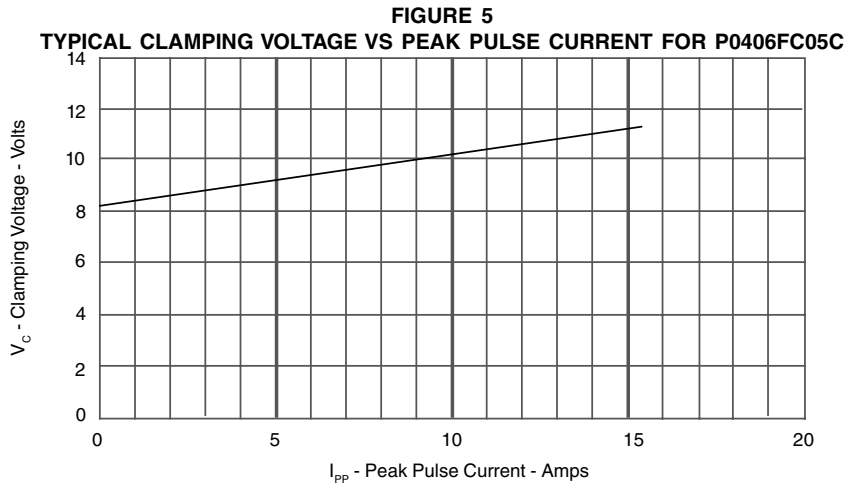
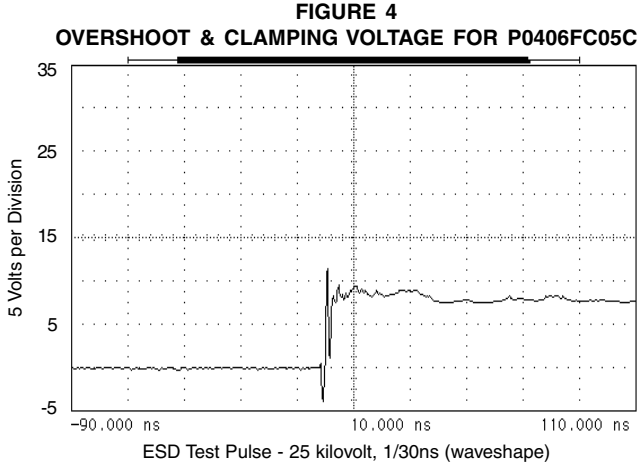
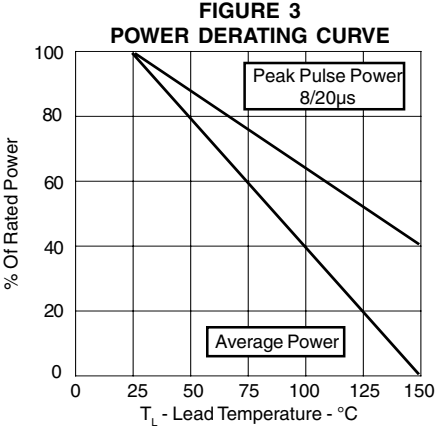
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	250	Watts
Operating Temperature	T_J	-55°C to 150°C	°C
Storage Temperature	T_{STG}	-55°C to 150°C	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified						
PART NUMBER (See Note 1)	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT (See Note 2)	TYPICAL CAPACITANCE
		@ 1mA $V_{(BR)}$ VOLTS	@ $I_p = 1A$ V_C VOLTS	@ 8/20 μs $V_C @ I_{PP}$	@ V_{WM} I_D μA	@ 0V, 1 MHz C pF
P0406FC3.3C	3.3	4.0	7.0	12.5V @ 20A	75*	150
P0406FC05C	5.0	6.0	9.8	14.7V @ 17A	10**	100
P0406FC08C	8.0	8.5	13.4	19.2V @ 13A	10***	75
P0406FC12C	12.0	13.3	19.0	29.7V @ 9.0A	1	50
P0406FC15C	15.0	16.7	24.0	35.7V @ 7.0A	1	40
P0406FC24C	24.0	26.7	43.0	55.0V @ 5.0A	1	30
P0406FC36C	36.0	40.0	64.0	84.0V @ 3.0A	1	25

Note 1: All devices are bidirectional. Electrical characteristics apply in both directions.
Note 2: *Maximum leakage current < 5 μA @ 2.8V. **Maximum leakage current < 500nA @ 3.3V. ***Maximum leakage current < 200nA @ 5V.



GRAPHS

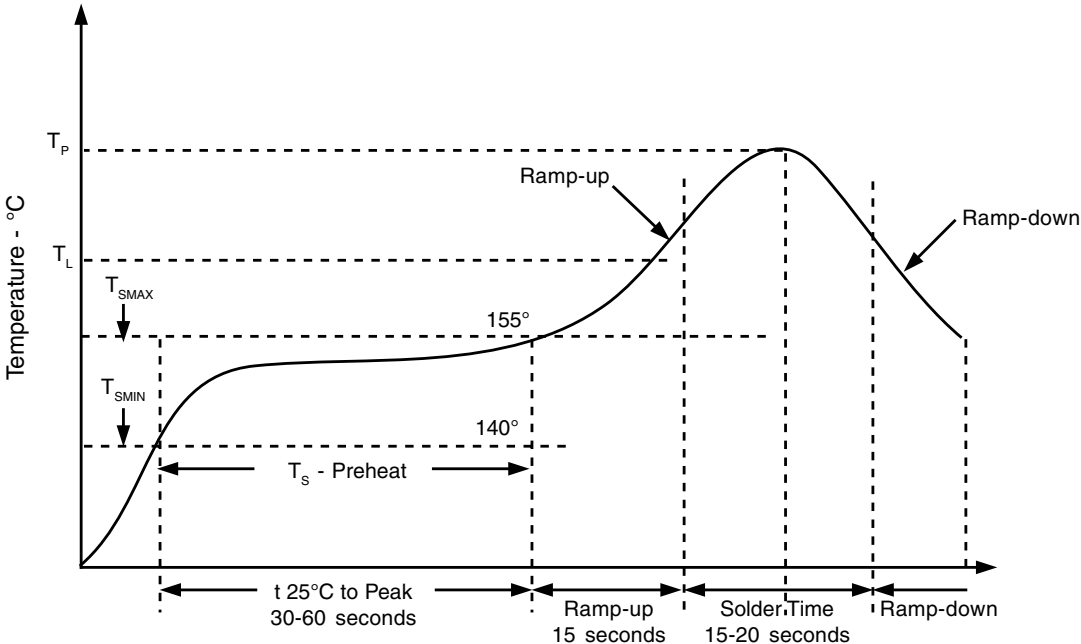
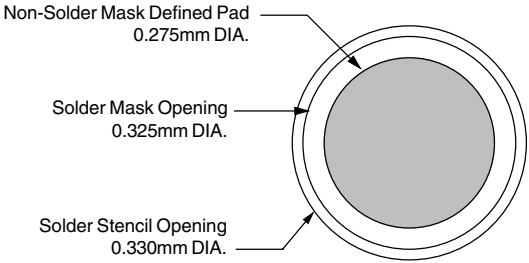


APPLICATION INFORMATION

PRINTED CIRCUIT BOARD RECOMMENDATIONS	
PARAMETER	VALUE
Pad Size on PCB	0.275mm
Pad Shape	Round
Pad Definition	Non-Solder Mask Defined Pads
Solder Mask Opening	0.325mm Round
Solder Stencil Thickness	0.150mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.330mm Round
Solder Paste Type	No Clean
Pad Protective Finish	OSP(Entek Cu Plus 106A)
Tolerance - Edge To Corner Ball	±50µm
Solder Ball Side Coplanarity	±20µm
Maximum Dwell Time Above Liquidous (183°C)	60 Seconds
Soldering Maximum Temperature	270°C

REQUIREMENTS
<p>Temperature: T_p for Lead-Free (SnAgCu): 260-265°C T_p for Tin-Lead: 240-245°C Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area & plating.</p>

RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION



P0406FC3.3C* thru P0406FC36C*

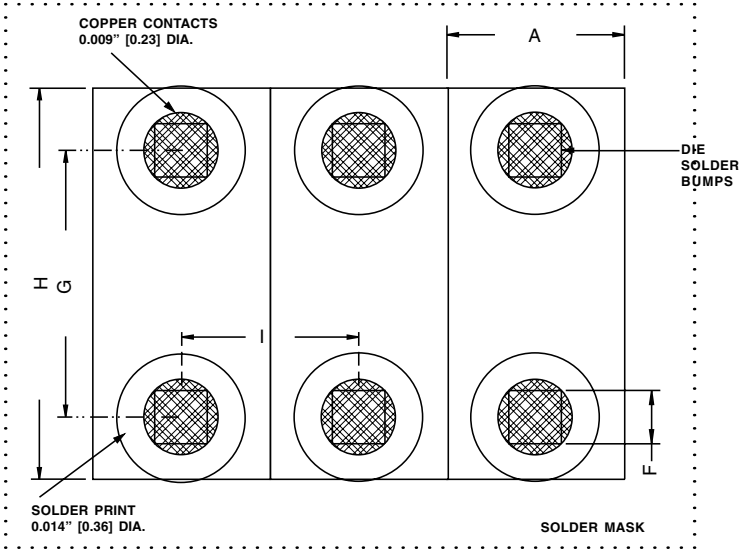
PACKAGE OUTLINE & DIMENSIONS

PACKAGE OUTLINE		PACKAGE DIMENSIONS		
		DIM	MILLIMETERS	INCHES
A	0.56 NOM	0.022 NOM		
B	0.86 NOM	0.034 NOM		
C	0.99 ± 0.0254	0.039 ± 0.001		
E	0.15 SQ	0.006 SQ		
F	1.5 ± 0.0254	0.059 ± 0.001		
G	0.15 NOM	0.006 NOM		
H	0.127 MAX 0.076 MIN	0.005 MAX 0.003 MIN		
I	0.406 NOM	0.016 NOM		
<p>NOTES:</p> <ol style="list-style-type: none"> Controlling dimensions in inches. Decimal tolerances for mounting pad and outline: $.xxx \pm 0.05\text{mm}$ (± 0.002”). 				
MOUNTING PAD LAYOUT - Option 1		PAD DIMENSIONS		
		DIM	MILLIMETERS	INCHES
A	0.51	0.020		
C	0.30	0.012		
D	0.46	0.018		
E	0.20	0.008		
F	0.15 SQ	0.006 SQ		
G	0.71	0.028		
H	0.99	0.039		
I	0.51	0.020		
<p>NOTE:</p> <ol style="list-style-type: none"> <i>Preferred:</i> Using 0.1mm (0.004”) stencil. 				
Outline & Dimensions: Rev 3 - 11/02, 06023				

P0406FC3.3C* thru P0406FC36C*

PACKAGE OUTLINE & DIMENSIONS

MOUNTING PAD LAYOUT - Option 2



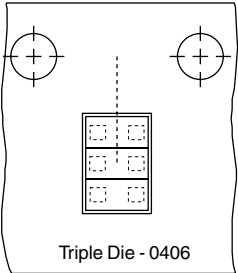
PACKAGE DIMENSIONS

DIM	MILLIMETERS	INCHES
A	0.51	0.020
F	0.15 SQ	0.006 SQ
G	0.71	0.028
H	0.99	0.039
I	0.51	0.020

- NOTES:**
1. Controlling dimensions in inches.
 2. Decimal tolerances for mounting pad and outline: .xxx ± 0.05mm (± 0.002").
 3. Preferred: Using 0.1mm (0.004") stencil.

Outline & Dimensions: Rev 3 - 11/02, 06023

TAPE & REEL ORIENTATION



- NOTE:**
1. Top view of tape. Solder bumps are face down in tape package.

TAPE & REEL ORDERING NOMENCLATURE

1. Surface mount product is taped and reeled in accordance with EIA 481.
2. 8mm Plastic Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-1 (i.e., P0406FC05C-T75-1).
3. 8mm Paper Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-2 (i.e., P0406FC05C-T75-2).
4. Suffix - LF = Lead-Free, i.e., P0406FC05C-LF-T75-2.

COPYRIGHT © ProTek Devices 2005
 SPECIFICATIONS: ProTek reserves the right to change the electrical and or mechanical characteristics described herein without notice (except JEDEC).
 DESIGN CHANGES: ProTek reserves the right to discontinue product lines without notice, and that the final judgement concerning selection and specifications is the buyer's and that in furnishing engineering and technical assistance, ProTek assumes no responsibility with respect to the selection or specifications of such products.

ProTek Devices
 2929 South Fair Lane, Tempe, AZ 85282
 Tel: 602-431-8101 Fax: 602-431-2288
 E-Mail: sales@protekdevices.com
 Web Site: www.protekdevices.com